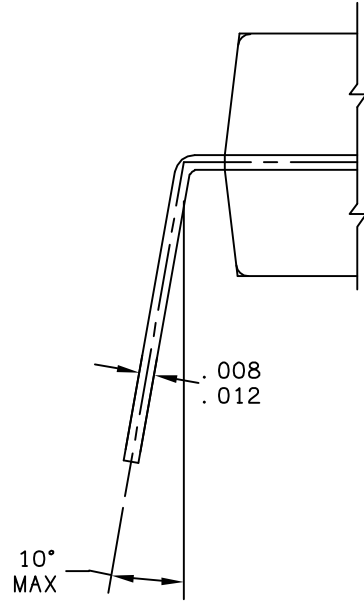


⊕ ∅ .005 Ⓜ C A Ⓜ B Ⓜ

| | | |
|---|---------------------------|-----------------------------------|
| © NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED | MECHANICAL OUTLINE | PRINT VERSION NOT TO SCALE |
| TITLE: 8 LD PDIP | DOCUMENT NO: 98ASB42420B | REV: P |
| | STANDARD: NON-JEDEC | |
| | SOT97-3 | 29 JAN 2016 |



DETAIL "D"

| | | | |
|---|--------------------|----------------------------|-------------|
| © NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED | MECHANICAL OUTLINE | PRINT VERSION NOT TO SCALE | |
| TITLE: 8 LD PDIP | | DOCUMENT NO: 98ASB42420B | REV: P |
| | | STANDARD: NON-JEDEC | |
| | | SOT97-3 | 29 JAN 2016 |



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M – 1994.
2. ALL DIMENSIONS ARE IN INCHES.
3. 626-03 TO 626-06 OBSOLETE. NEW STANDARD 626-07.
4. DIMENSION TO CENTER OF LEAD WHEN FORMED PARALLEL.
5. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CONERS).

STYLE 1:

| | | | | |
|-----|----|---------|----|-----------|
| PIN | 1. | AC IN | 5. | GROUND |
| | 2. | DC + IN | 6. | OUTPUT |
| | 3. | DC – IN | 7. | AUXILIARY |
| | 4. | AC IN | 8. | VCC |

| | | |
|---|--------------------------|----------------------------|
| © NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED | MECHANICAL OUTLINE | PRINT VERSION NOT TO SCALE |
| TITLE: 8 LD PDIP | DOCUMENT NO: 98ASB42420B | REV: P |
| | STANDARD: NON-JEDEC | |
| | SOT97-3 | 29 JAN 2016 |